

Tflex™ SF10 Application Guide

Shelf Life:

Shelf life for Tflex SF10 is 1 year from date of shipment at the storage conditions specified below.

Storage Conditions:

Recommended storage conditions are 0-35°C and relative humidity of 50% maximum. Store in original product packaging until ready for use.

It is not recommended to store this product under excessive weight, as the product is susceptible to deflection at very low pressure.

Storage After Applied to a Component:

It is recommended to keep product covered and clean after applying it to a component and stored at ambient conditions.

Handling of Material:

A light, visible and consistent residue on the liner is normal for this product and it will not affect the product's performance.

The gap filler product is designed to be easily deflected in application (high compliancy) and can therefore stretch or compress when handled.

During shipping and handling, the gap filler product can prematurely release from areas of the carrier liner. The premature release is visibly noticeable as voids or bubbles between liner and gap filler. This behavior does not impact the performance of the product as long the thickness remains in tolerance (+/- 10% of nominal thickness).



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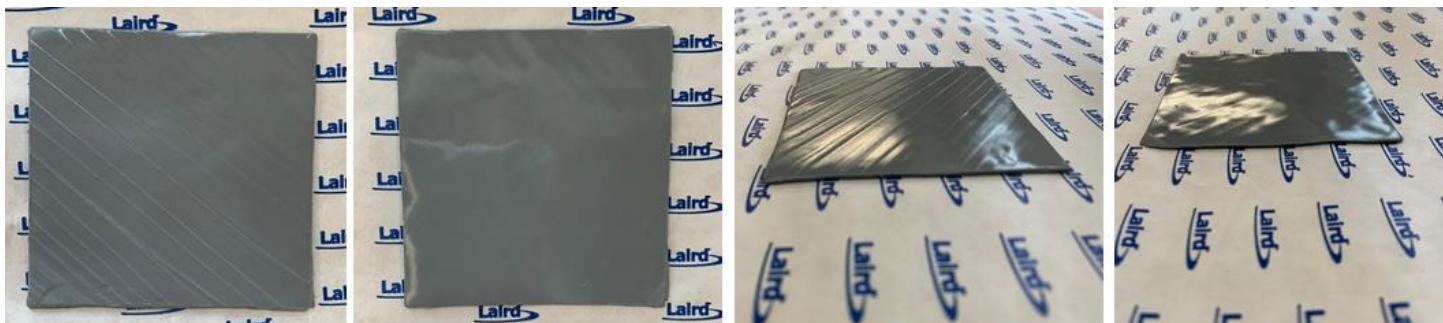
Cut-Through Part Peeling Instructions:

Peel back one liner by separating it from the pad at one corner. Peel back the liner in one swift, consistent motion as close to an 180° angle as possible.

Peel off the remaining clear liner by separating it from the pad at one corner. Peel back the liner in one swift, consistent motion as close to an 180° angle as possible. Ensure you are peeling the liner from the pad. Do not attempt to grasp the pad and peel it from the liner.

Cut-Through Part Peeling Instructions (Continued):

Peeling in a swift, consistent motion will result in a release with minimal pull out and a tacky pad surface. Do not stop to inspect during the peeling process or ridges in the pad may occur. These ridges will press out under light pressure of the application however and will not impact thermal performance of the product.



Cut-Through Part Application Instructions:

1. Remove the embossed (diamond) liner by separating it from the pad at one corner. Peel back the liner in one swift, consistent motion as close to an 180° angle as possible.
2. Place the exposed side of the gap filler on the desired substrate by applying slight force to ensure the gap filler sticks.
3. Peel off the remaining clear or embossed liner by separating it from the pad at one corner. Peel back the liner in one swift, consistent motion as close to an 180° angle as possible.



Separation of Components and Removal of Tflex SF10

To remove Tflex SF10, its recommended to heat the component and scrape away remaining parts of the pad. It is common for residue to be left after removing the pad from use. Residue can be wiped away with a dry cloth. If excess residue remains, it can be cleaned further with mineral spirits, followed by acetone.